

### AMENDMENTS TO THE CLAIMS

1. (Presently Amended) A circuit package for an electronic device, comprising:
  - a first circuit board positioned in a first plane;
  - a second circuit board positioned in a second plane;
  - at least one brace positioned between the first and second circuit boards, the brace formed to affix coupled to the first circuit board to and the second circuit board, wherein the brace is operable to function as a flexible spacer between the first and second circuit boards;
  - at least two electrically conductive leads extending from at least one external surface of the circuit package; and
  - a housing formed between the first and second circuit boards, wherein the housing is formed and configured to surround substantially cover at least one side surface of the each circuit board, thereby allowing one and leave another surface of each circuit board to be substantially uncovered to thereby exposed the uncovered surface to the exterior surface an environment exterior of the circuit package.
2. (Presently Amended) The circuit package of Claim 1, wherein the housing forms comprises a bottom surface between at least two electrically conductive leads of the circuit package, wherein the bottom surface of the circuit package comprises that includes a cavity formed therein.
3. (Presently Amended) The circuit package of Claim 1, wherein the first and second circuit boards are each made of a single-sided direct bonded copper substrate.
4. (Presently Amended) The circuit package of Claim 1, wherein the brace comprises:
  - an elongated body;
  - at least two arm portions positioned to extend extending from the body, wherein the arm portions are configured to affix at least one of the arm portions coupled to the first circuit board and another of the arm portions coupled to the second circuit board; and
  - at least to leg portions positioned to extend extending from the body, wherein the two leg portions are each leg portion operable to function as a flexible spacer between the first and second circuit boards.

5. (Presently Amended) The circuit package of Claim 1, wherein the circuit package comprises a first brace and a second brace, each brace positioned between the first and second circuit boards, the first and second braces affix and coupling the first circuit board to the second circuit board, the first and second braces are operable to function as a flexible spacer between the first and second circuit boards.
6. (Presently Amended) The circuit package of Claim 1, further comprising:  
a plurality of electrically conductive leads, ~~wherein the plurality of electrically conductive leads are adapted for to mounting the circuit package on an external surface, and wherein the plurality of electrically conductive leads are configured to support the circuit package in an upright position relative to the external surface.~~
7. (Presently Amended) The circuit package of Claim 1, wherein the housing includes an external surface of the housing forms a configured to be substantially flush surface with the exposed substantially uncovered surfaces of each circuit board.
8. (Original) The circuit package of Claim 1, wherein the housing is made from an injected molded plastic.
9. (Presently Amended) The circuit package of Claim 1, further comprising:  
an H-bridge circuit mounted on at least one of the first and second circuit boards.
10. (Presently Amended) The circuit package of Claim 7, wherein the H-bridge circuit comprises:  
a first switch in a first leg including of the H-bridge output circuit coupled between a first lead and a first output node, and a first switch coupled therebetween;  
a second switch in a second leg including of the H-bridge output circuit coupled between a second lead and a second output node, and a second switch coupled therebetween;  
a third switch in a third leg including of the H-bridge output circuit coupled between the first lead and the second output node, and a third switch coupled therebetween;  
a first switch in a fourth leg including of the H-bridge output circuit coupled between the second lead and the first output node, and a fourth switch coupled therebetween.

11. (Presently Amended) A circuit package for an electronic device, comprising:  
a first circuit board positioned in a first plane;  
a second circuit board positioned in a second plane, ~~wherein the first and second circuit boards are positioned against one another and in contact with the first circuit board;~~  
at least one brace ~~operable to affix~~ coupled to the first circuit board ~~to~~ and the second circuit board;  
a plurality of electrically conductive leads extending from ~~at least one external surface of~~ the circuit package, ~~the plurality of electrically conductive leads~~ and adapted to mount the circuit package on an external surface ~~in an upright position;~~ and  
a housing formed to surround at least a portion of the first and second circuit boards ~~and a plurality of components mounted on the first and second circuit boards.~~
12. (Presently Amended) The circuit package of Claim 11, wherein the housing forms a surface between at least two electrically conductive leads of the circuit package, wherein the surface of the circuit package comprises a cavity formed therein.
13. (Original) The circuit package of Claim 11, wherein the first and second circuit boards are made of a single-sided direct bonded copper substrate.
14. (Presently Amended) The circuit package of Claim 11, wherein the brace ~~is operable to function as an electrical~~ conductor ~~between a plurality of circuit components on the first and second circuit boards.~~
15. (Original) The circuit package of Claim 11, wherein the housing is made from an injected molded plastic.
16. (Presently Amended) The circuit package of Claim 11, further comprising:  
an H-bridge circuit mounted on at least one of the first and second circuit boards.

17. (Presently Amended) The circuit package of Claim 16, wherein the H-bridge circuit comprises:

~~a first switch in a first leg including of the H-bridge output circuit coupled between a first lead and a first output node, and a first switch coupled therebetween;~~

~~a second switch in a second leg including of the H-bridge output circuit coupled between a second lead and a second output node, and a second switch coupled therebetween;~~

~~a third switch in a third leg including of the H-bridge output circuit coupled between the first lead and the second output node, and a third switch coupled therebetween;~~

~~a first switch in a fourth leg including of the H-bridge output circuit coupled between the second lead and the first output node, and a fourth switch coupled therebetween.~~

18. (Presently Amended) A method ~~for~~ of manufacturing a circuit package, ~~wherein the method comprises comprising the steps of:~~

positioning a first circuit board in a first plane;

positioning a second circuit board in a second plane;

~~affixing coupling at least two brace members between the first and second circuit boards, thereby affixing to the first circuit board to the second circuit boards;~~

mounting at least two electrically conductive leads to at least one edge of the first and second circuit boards; and

~~forming a housing by injecting a molding material between the first and second circuit boards, thereby forming a top surface and a bottom surface that extend between the first and second circuit boards, wherein the housing is configured to form a housing that substantially covers at least one surface of each of the circuit boards and leaves another surface of each circuit board substantially uncovered to thereby expose at least one surface of the first and second circuit boards.~~

19. (Presently Amended) The method of Claim 18, further comprising the step of:  
~~mounting coupling~~ a plurality of conductive leads to the first and second circuit boards.

20. (New) The circuit package of Claim 11, further comprising:  
a plurality of components mounted on the first and second circuit boards in a region that is surrounded by the housing.